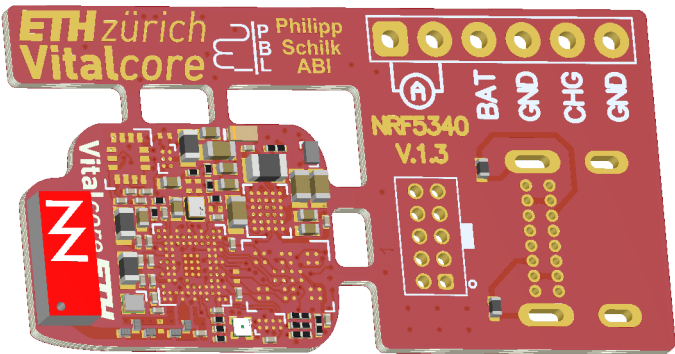
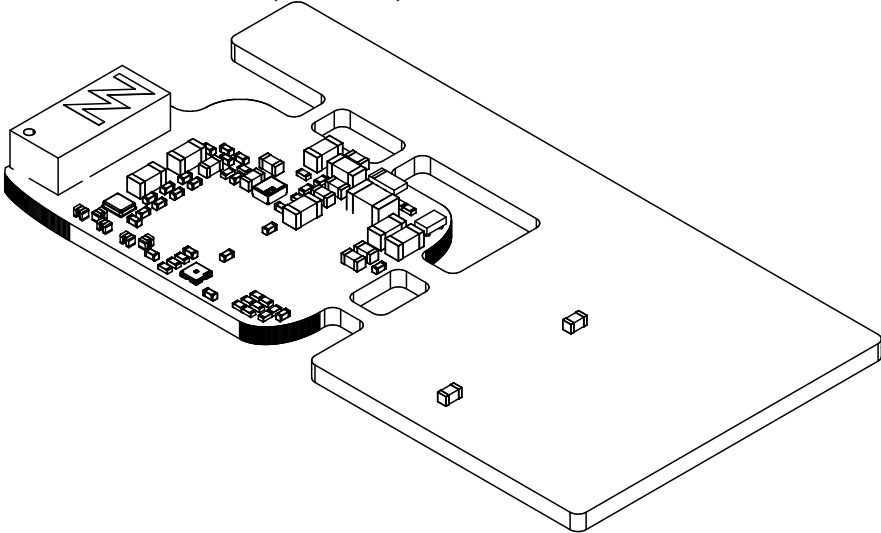


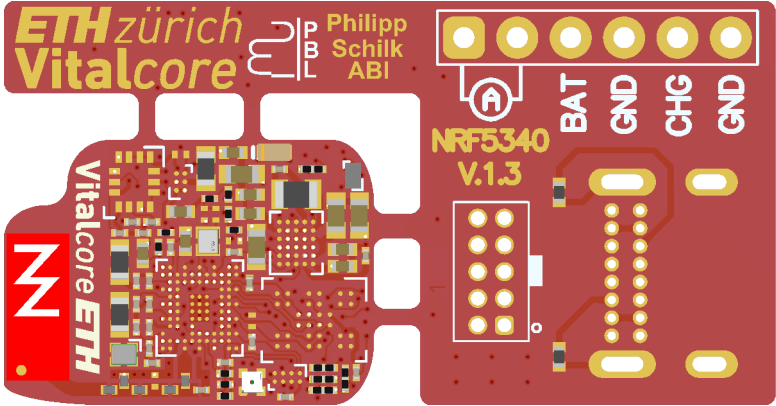
Realistic View



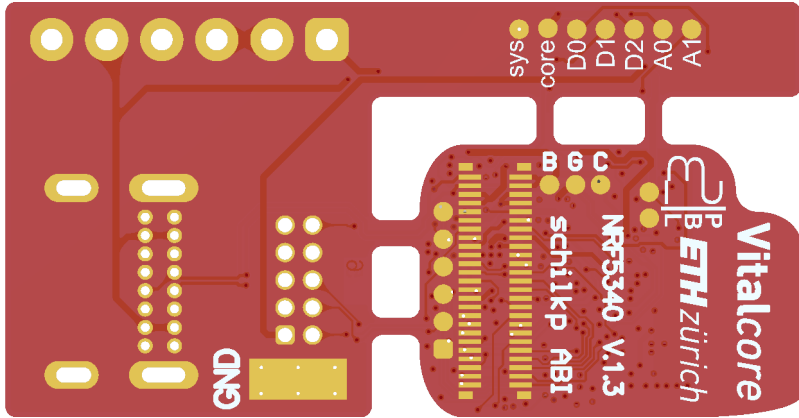
View from Front side (Scale 3:1)



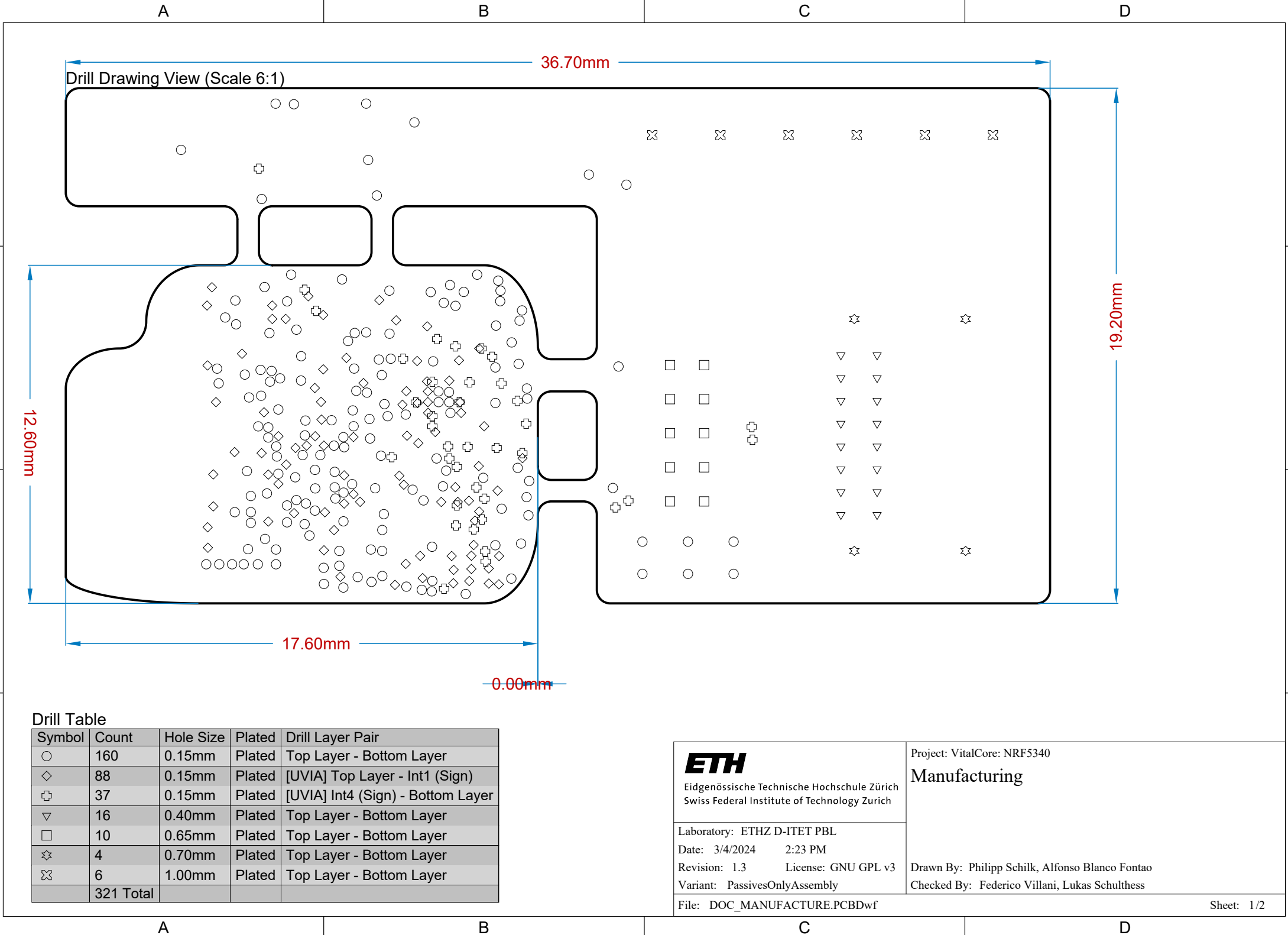
Realistic View



Realistic View



| | |
|---|---|
| <div><div><div>ETH</div><div>Eidgenössische Technische Hochschule Zürich</div><div>Swiss Federal Institute of Technology Zurich</div></div></div> | Project: VitalCore: NRF5340 |
| | 3D Render |
| Laboratory: ETHZ D-ITET PBL | Drawn By: Philipp Schilk, Alfonso Blanco Fontao |
| Date: 3/4/2024 2:23 PM | |
| Revision: 1.3 License: GNU GPL v3 | Checked By: Federico Villani, Lukas Schulthess |
| Variant: PassivesOnlyAssembly | |
| File: DOC_3D.PCBDwf | Sheet: 1/1 |



Drill Table

| Symbol | Count | Hole Size | Plated | Drill Layer Pair |
|--------|-----------|-----------|--------|-----------------------------------|
| ○ | 160 | 0.15mm | Plated | Top Layer - Bottom Layer |
| ◇ | 88 | 0.15mm | Plated | [UVIA] Top Layer - Int1 (Sign) |
| ⊕ | 37 | 0.15mm | Plated | [UVIA] Int4 (Sign) - Bottom Layer |
| ▽ | 16 | 0.40mm | Plated | Top Layer - Bottom Layer |
| □ | 10 | 0.65mm | Plated | Top Layer - Bottom Layer |
| ☆ | 4 | 0.70mm | Plated | Top Layer - Bottom Layer |
| ⊗ | 6 | 1.00mm | Plated | Top Layer - Bottom Layer |
| | 321 Total | | | |

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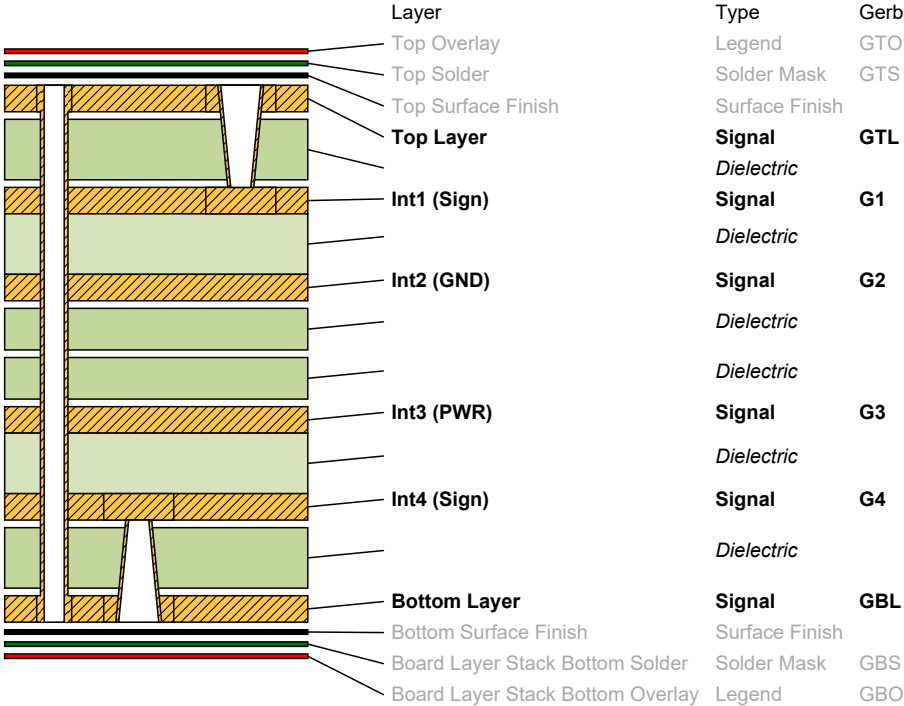
Laboratory: ETHZ D-ITET PBL
Date: 3/4/2024 2:23 PM
Revision: 1.3 License: GNU GPL v3
Variant: PassivesOnlyAssembly
File: DOC_MANUFACTURE.PCBDwf

Project: VitalCore: NRF5340
Manufacturing

Drawn By: Philipp Schilk, Alfonso Blanco Fontao
Checked By: Federico Villani, Lukas Schulthess

Sheet: 1/2

Layer Stack Legend



NOTES:

- HDI/Buried Via.
- Via in pad.
- 0.8mm Board: Use PCBWAY standard stackup (see left).
- ENIG finish.
- Red solder mask.

Use standard PCBWAY 6layer/0.8mm stackup:

| Thickness | Copper thick (outer/inner) | Layer No. | StackUp | Laminated chart Thickness |
|-------------|----------------------------|-----------|---------|---|
| 0.8mm±0.1mm | 1/1oz | L1 | | Copper 18 um--plating to 35um |
| | | | | PP 0.11 mm(2116) dielectric constant 4.29 ± (The DK value is not absolute and will vary depending on the base material's models and thickness.) |
| | | L2 | | |
| | | L3 | | Core 0.2mm with 1/1 oz Cu |
| | | | | PP 0.11 mm(2116) dielectric constant 4.29 ± (The DK value is not absolute and will vary depending on the base material's models and thickness.) |
| | | L4 | | |
| | | L5 | | Core 0.2mm with 1/1 oz Cu |
| | | | | PP 0.11 mm(2116) dielectric constant 4.29 ± (The DK value is not absolute and will vary depending on the base material's models and thickness.) |
| | | L6 | | |
| | | | | Copper 18 um--plating to 35um |
| | | | | |
| | | | | |

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File: DOC_MANUFACTURE.PCBDwf

Project: VitalCore: NRF5340

Manufacturing

Drawn By: Philipp Schilk, Alfonso Blanco Fontao
Checked By: Federico Villani, Lukas Schulthess

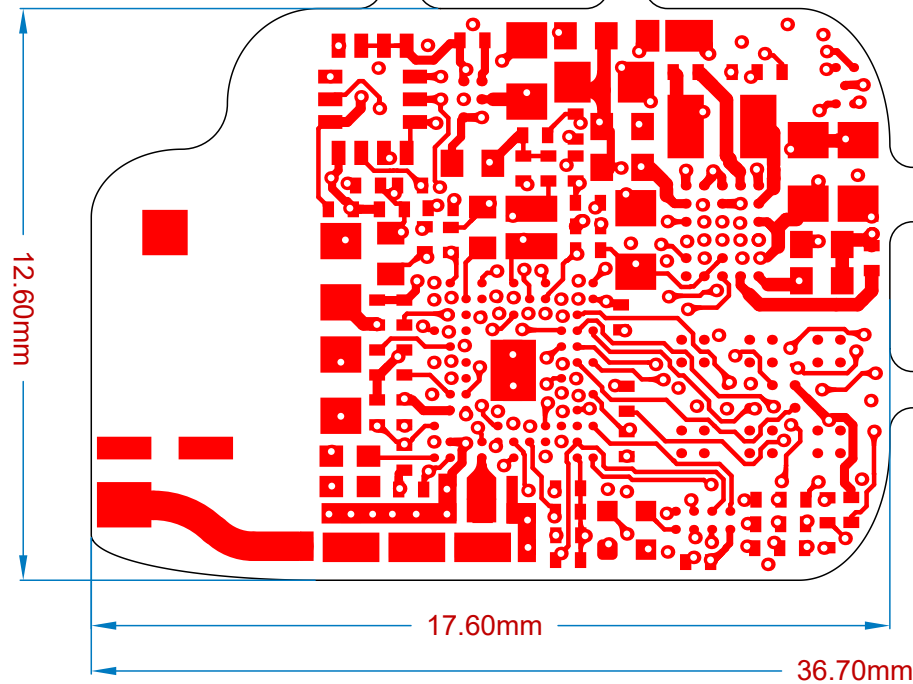
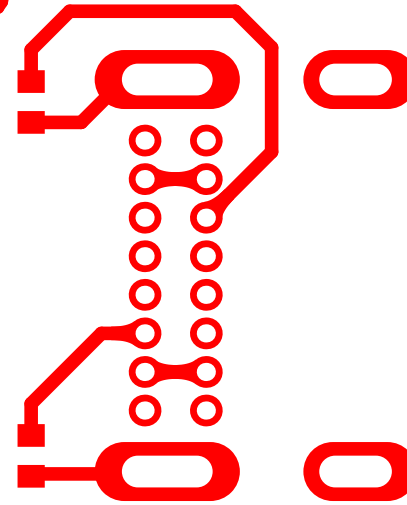
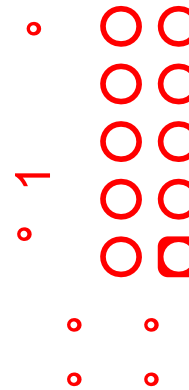
Top Layer (Scale 6:1)

ETH zürich
Vitalcore

Philipp
Schilk
ABI



NRF5340
V.1.3



19.20mm

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Swiss Federal Institute of Technology Zurich

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Revision: 1.3 License: GNU GPL v3

Variant: PassivesOnlyAssembly

File: DOC_ART.PCBDwf

Project: VitalCore: NRF5340

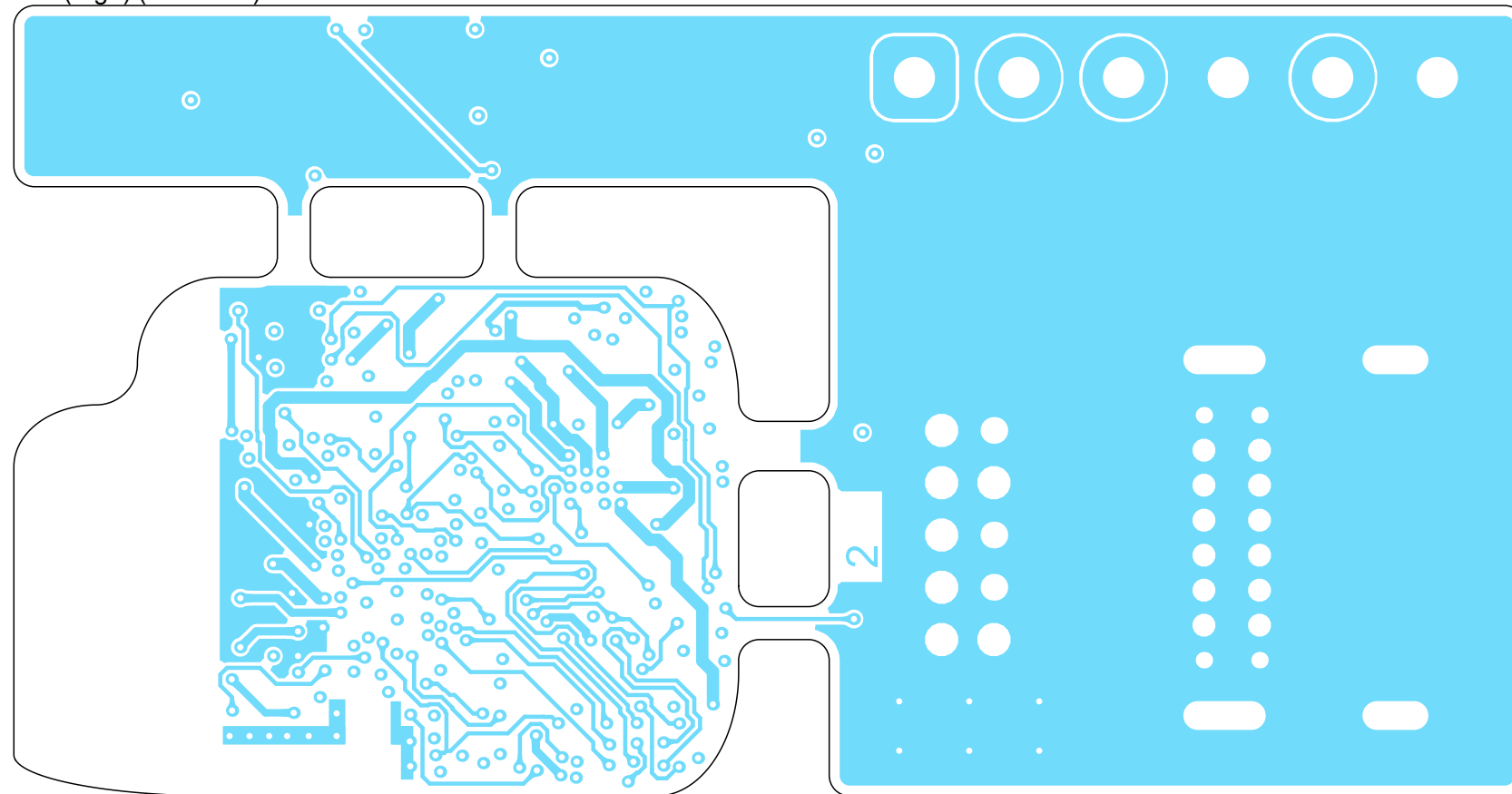
Art

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Sheet: 1/6

Int1 (Sign) (Scale 6:1)



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Variant: PassivesOnlyAssembly

File: DOC_ART.PCBDwf

Project: VitalCore: NRF5340

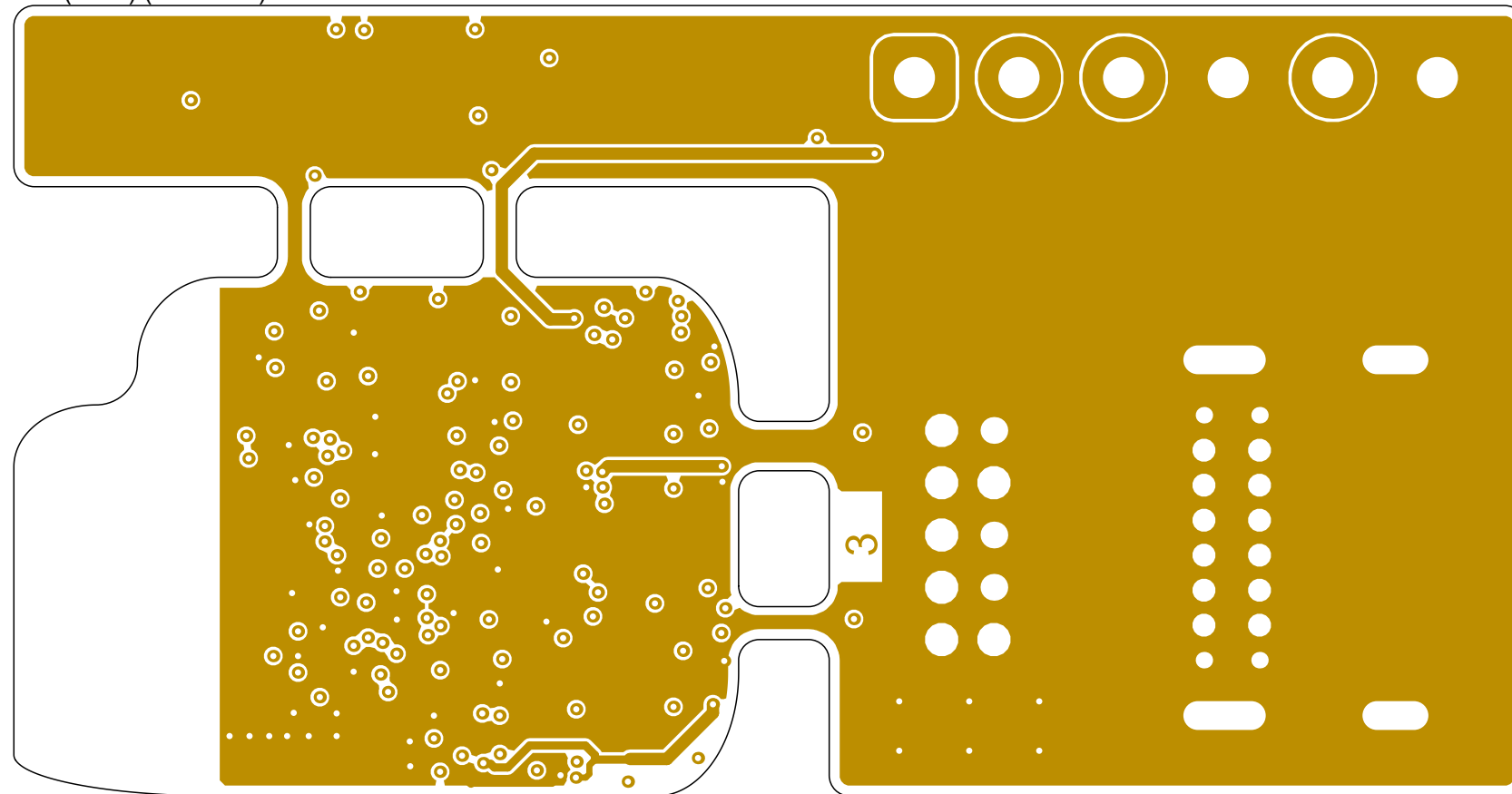
Art

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Sheet: 2/6

Int2 (GND) (Scale 6:1)



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Variant: PassivesOnlyAssembly

File: DOC_ART.PCBDwf

Project: VitalCore: NRF5340

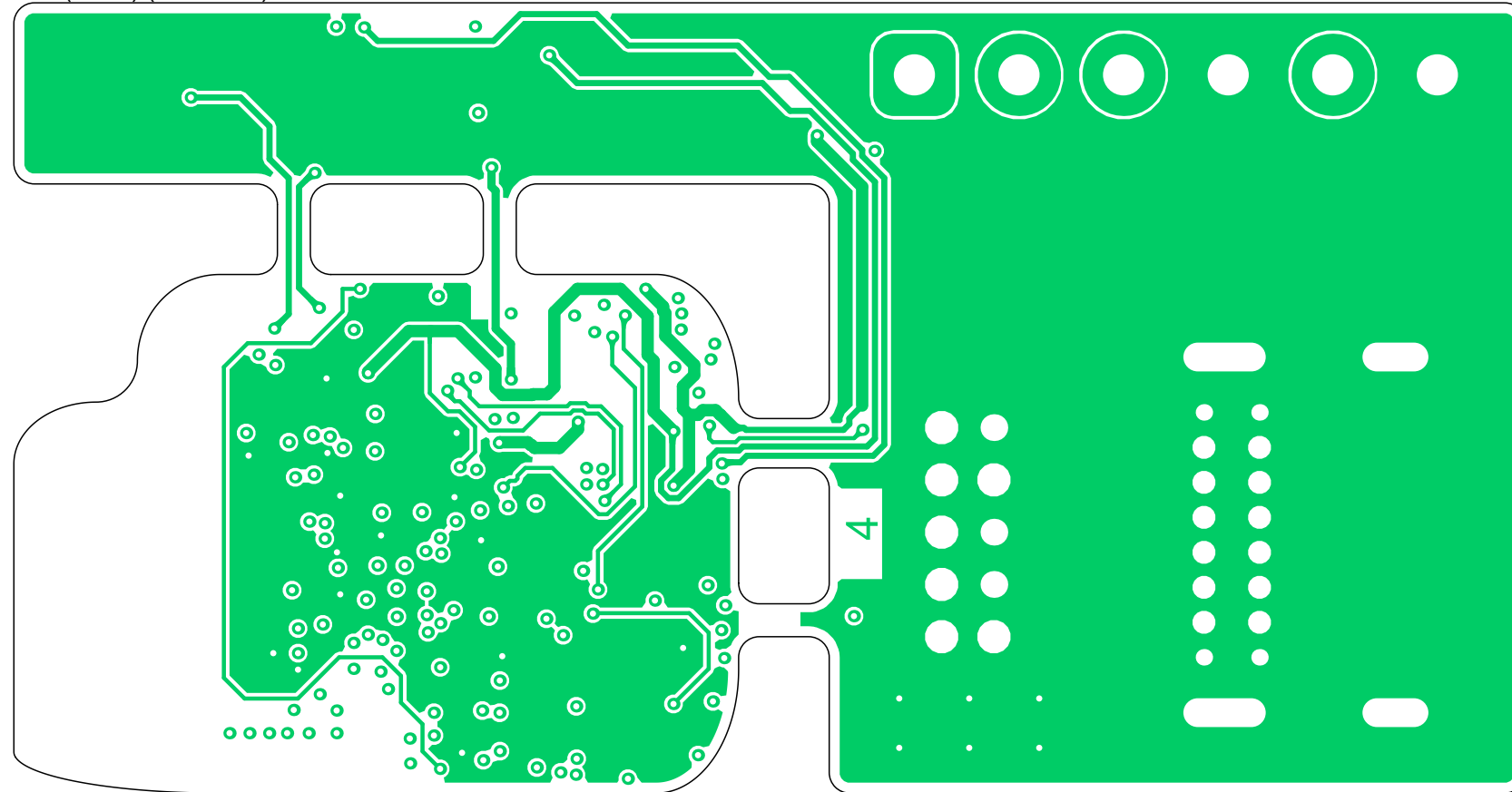
Art

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Sheet: 3/6

Int3 (PWR) (Scale 6:1)



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Variant: PassivesOnlyAssembly

File: DOC_ART.PCBDwf

Project: VitalCore: NRF5340

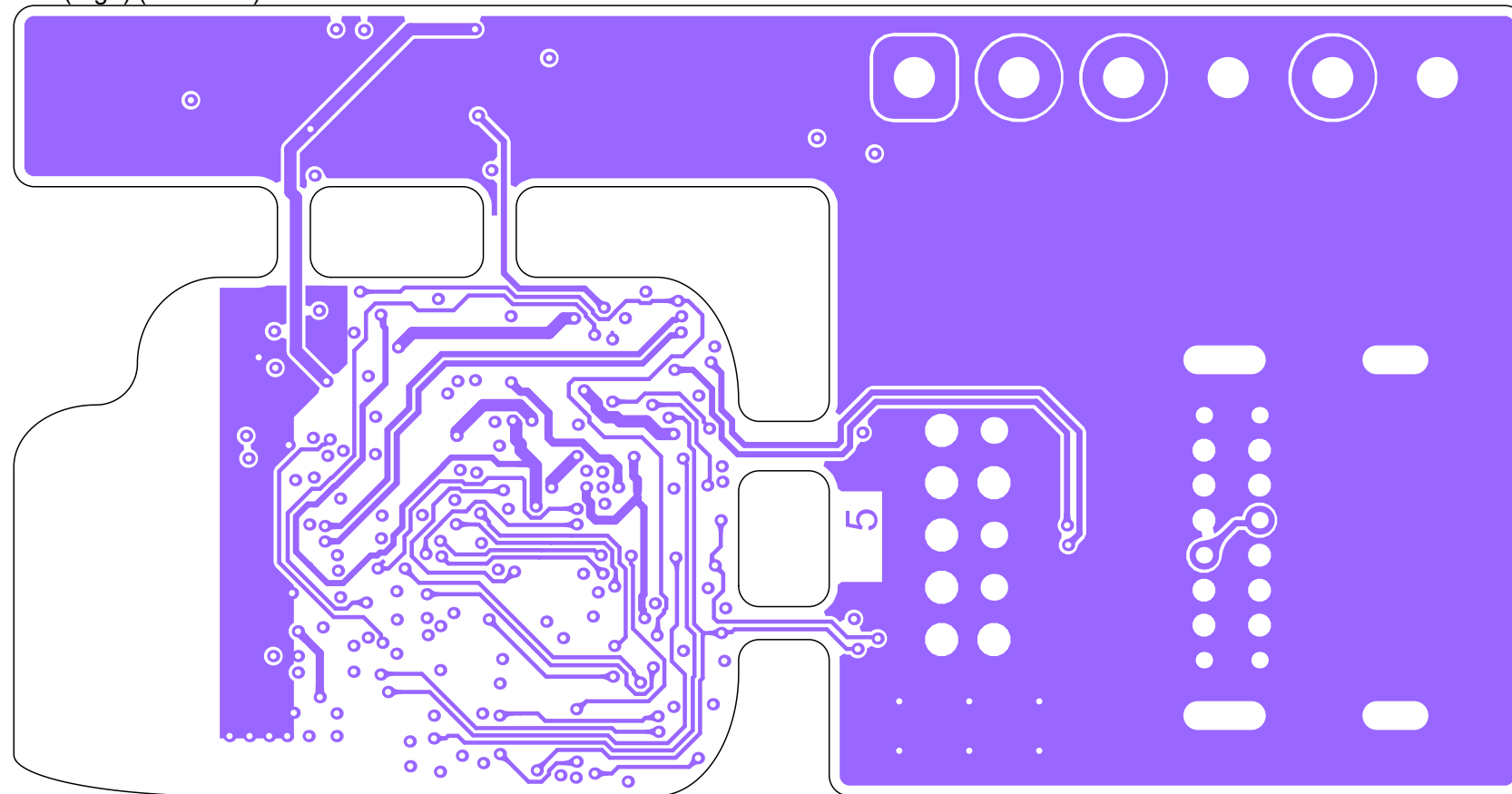
Art

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Checked By: Federico Villani, Lukas Schulthess

Sheet: 4/6

Int4 (Sign) (Scale 6:1)



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Revision: 1.3 License: GNU GPL v3

Variant: PassivesOnlyAssembly

File: DOC_ART.PCBDwf

Project: VitalCore: NRF5340

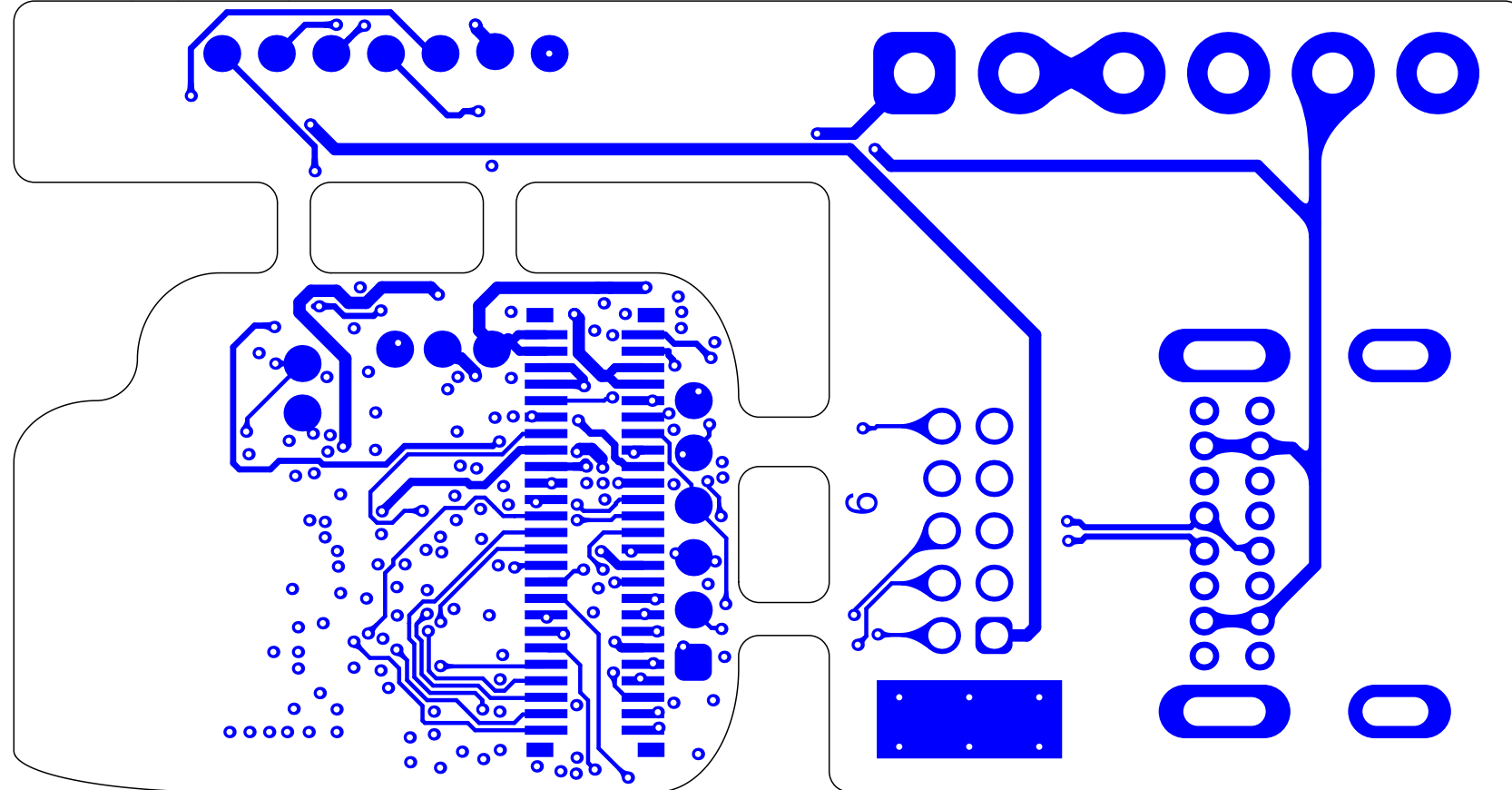
Art

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Sheet: 5/6

Bottom Layer (Scale 6:1)



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Revision: 1.3 License: GNU GPL v3
Variant: PassivesOnlyAssembly
File: DOC_ART.PCBDwf

Project: VitalCore: NRF5340

Art

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Checked By: Federico Villani, Lukas Schulthess

Sheet: 6/6